

Toshiba Intelligent Power Device Silicon Monolithic Power MOS Integrated Circuit

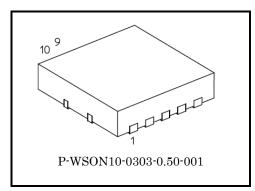
# TPD1058FA

Low-Side Switch for Solenoid, Motor and Lamp Drive

The TPD1058FA is a monolithic power IC for low-side switches. The IC has a MOSFET (DMOS) output which can be directly driven from a CMOS or TTL logic circuit (e.g., an MPU). The IC is equipped with intelligent self-protective functions and diagnostic functions.

#### **Features**

- A monolithic power IC with a new structure combining a control block and a power MOSFET (DMOS) on single chip.
- AEC-Q100 qualified.
- Can directly drive a power load from CMOS or TTL logic.
- Built-in protection against overvoltage (active clamp), over temperature (thermal shutdown), and over current.



Weight: 0.02 g (typ.)

- Incorporates a diagnosis function that allows diagnosis output to be read externally at load short-circuiting, opening, or over temperature
- Low Drain-Source ON-resistance:

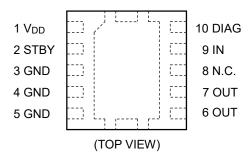
$$R_{DS(ON)} = 0.1 \Omega (Max) @V_{DD} = 5 V, V_{STBY} = V_{IN} = 5V, I_O = 2 A, T_{ch} = 25 °C$$

Low Standby Current:

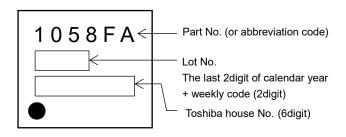
$$I_{DD} = 10 \mu A \text{ (Max)} @V_{STBY} = V_{IN} = 0 \text{V}, V_{DD} = 5 \text{V}, T_{ch} = -40 \text{ to } 125 ^{\circ}\text{C}$$

WSON10 package with embossed-tape packing.

# Pin Assignment (top view)



# Marking



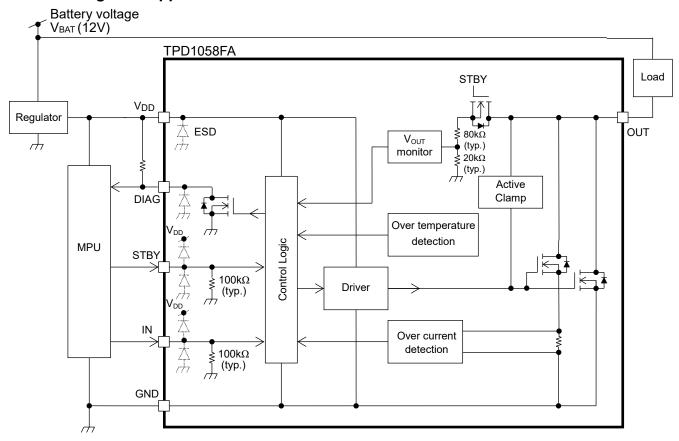
on the lower left of the marking indicates Pin 1

Note: Due to its MOS structure, this product is sensitive to static electricity.

Start of commercial production 2015-04



# **Block Diagram / Application Circuit**



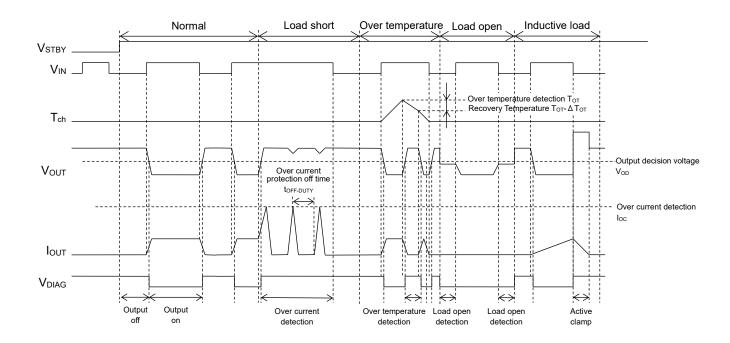
Note1: The value in block diagram is a standard value in Tch = 25°C.



**Pin Description** 

Pin No.	Symbol	Pin Description				
1	$V_{DD}$	Power supply pin.				
2	STBY	Standby pin. This pin has an internal pull-down resistor (100kΩ (typ.)). In the case of open state, it becomes standby mode same as V <sub>STBY</sub> =V <sub>IL</sub> .  V <sub>STBY</sub> =V <sub>IL</sub> : I <sub>DD</sub> ≤10μA (Standby mode)  V <sub>STBY</sub> =V <sub>IH</sub> : Active control				
3,4,5	GND	Ground pin.				
6,7	OUT	Output pin. When a load short-circuit causes an overcurrent (6A min) to flow into a device, output current is limited in order to protect the IC.				
8	N.C.	No-Connect pin. (not connected to the chip.)				
9	IN	Input pin. The IN pin has an internal pull-down resistor (100kΩ (typ.)). Even if the IN pin is open, the output will not accidentally turn on.				
10	DIAG	Self-diagnosis output pin. N-channel open drain.				

# **Timing chart**





#### Truth table

STBY	IN	OUT	DIAG	Output DMOS	Operating state		
L	L	Н	Н	OFF	Cton dhi cao do		
	Н	Н	Н	OFF	Standby mode		
Н	L	Н	Н	OFF	Normal eneration		
	Η	L	L	ON	Normal operation		
	L	Н	Н	OFF	Over current		
	Η	H(*1)	Н	ON/OFF	(Short to V <sub>BAT</sub> / GND)		
	L	Н	Н	OFF	Over temperature		
	Η	H(*1)	Н	OFF	Over temperature		
	L	L(*2)	L	OFF	Load open		
	Н	Ĺ	Ĺ	ON	(Disconnection)		

<sup>\*1:</sup> Case of STBY=H and IN=H, the output voltage conditions to output a diagnosis are more than V<sub>OD</sub>. (V<sub>OUT</sub> > V<sub>OD</sub>)

<sup>\*2:</sup> Case of STBY=H and IN=L, the output voltage conditions to output a diagnosis are less than V<sub>OD</sub>. (V<sub>OUT</sub> < V<sub>OD</sub>)



#### Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	PIN	Rating	Unit	Note
Supply voltage	$V_{DD}$	$V_{DD}$	-0.3 to 6.0	V	-
Input voltage	$V_{\text{IN}}$ , $V_{\text{STBY}}$	IN,STBY	-0.3 to 6.0	V	-
DIAG output voltage	$V_{DIAG}$	DIAG	-0.3 to 6.0	V	-
DIAG output current	I <sub>DIAG</sub>	DIAG	5	mA	-
Output voltage	Vout	OUT	-0.3 to 40.0	V	N channel DMOS (V <sub>DSS</sub> =60V)
Output current	l <sub>OUT</sub>	OUT	Internally limited	Α	-
Power dissipation (Note 2)	P <sub>D</sub>	-	1.84	W	-
Single pulse active clamp capability (Note 3)	E <sub>AS</sub>	-	95	mJ	-
Active clamp current	I <sub>AR</sub>	OUT	6	Α	-
Operating temperature	Topr	-	-40 to 125	°C	-
Channel temperature	T <sub>ch</sub>	-	150	°C	-
Storage temperature	T <sub>stg</sub>	-	-40 to 150	°C	-

Note1:Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings and the operating ranges.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

## **Thermal Characteristics**

Characteristics	Symbol	bol Rating	
Thermal resistance, channel to ambient	Rth (ch-a)	67.6	°C/W

Note 2: Glass epoxy board Material: FR-4(4 layer)

Board size: 76.2mm×114.3mm×1.6mm

Via: Ø0.3mm(2 point)

Note 3: Active clamp capability (single pulse) test condition  $V_{DD}$ =12V,  $T_{ch}$  =25°C(initial), L=3.9 mH,  $I_{AR}$ =6 A



## **Electrical Characteristics**

# (Unless otherwise specified Tch = -40 to 125°C, VDD = 4.5 to 5.5V)

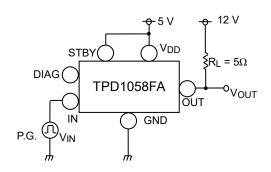
Characteristics	Symbol	Pin	Test condition	Min	Тур.	Max	Unit
Output clamp voltage	V <sub>(CL)DSS</sub>	OUT	I <sub>OUT</sub> =1mA, V <sub>STBY</sub> =5V, V <sub>IN</sub> =0V	40	46	60	V
Operating supply voltage	V <sub>DD(opr)</sub>	$V_{DD}$	-	4.5	5.0	5.5	V
Under voltage protection	$V_{DD(UV)}$	$V_{DD}$	-	2.5	2.9	3.5	V
	I <sub>DD1</sub>	$V_{DD}$	V <sub>STBY</sub> =0V,V <sub>IN</sub> =0V, V <sub>DD</sub> =5V,	-	0	10	μΑ
Supply current	I <sub>DD2</sub>	$V_{DD}$	V <sub>STBY</sub> =5V, V <sub>IN</sub> =0V, V <sub>DD</sub> =5V	-	0.61	2.00	mA
	I <sub>DD3</sub>	V <sub>DD</sub>	V <sub>STBY</sub> =5V, V <sub>IN</sub> =5V, V <sub>DD</sub> =5V	-	0.62	5.00	mA
Output le alcana accument	I <sub>OL1</sub>	OUT	V <sub>STBY</sub> =V <sub>IL</sub> , V <sub>IN</sub> =V <sub>IL</sub> , V <sub>OUT</sub> =8 to 16V	-	-	10	μΑ
Output leakage current	I <sub>OL2</sub>	OUT	V <sub>STBY</sub> =V <sub>IH</sub> , V <sub>IN</sub> =V <sub>IL</sub> , V <sub>OUT</sub> =8 to 16V	-	160	300	μΑ
High level input voltage	VIH	IN,STBY	-	2.0	-	-	V
Low level input voltage	VIL	IN,STBY	-	-	-	0.8	V
High level input current	I <sub>IH</sub>	IN,STBY	V <sub>IN</sub> (V <sub>STBY</sub> )=5V, V <sub>DD</sub> =5V	-	50	200	μΑ
Low level input current	I <sub>IL</sub>	IN,STBY	V <sub>IN</sub> (V <sub>STBY</sub> )=0V, V <sub>DD</sub> =5V	-1	-	1	μА
DIAG leakage current	I <sub>DH</sub>	DIAG	V <sub>DIAG</sub> =5V	-	-	3	μΑ
DIAG output voltage	$V_{DL}$	DIAG	I <sub>DIAG</sub> =+1mA	-	0.01	0.20	V
Output resistance	R <sub>DS(ON)1</sub>	OUT	I <sub>OUT</sub> =+2A, T <sub>ch</sub> =25°C, V <sub>DD</sub> =5V, V <sub>STBY</sub> =V <sub>IH</sub> ,V <sub>IN</sub> =V <sub>IH</sub>	-	0.07	0.10	Ω
(output DMOS on)	R <sub>DS(ON)2</sub>	OUT	I <sub>OUT</sub> =+2A, T <sub>ch</sub> =-40 to 125°C, V <sub>DD</sub> =5V, V <sub>STBY</sub> =V <sub>IH</sub> ,V <sub>IN</sub> =V <sub>IH</sub>	-	-	0.16	Ω
Over temperature	Тот	-	\\\-\(-\)\\\\\\\\\\\\\\\\\\\\\\\\\\	150	172	200	°C
detection	ΔТот	-	V <sub>STBY</sub> =V <sub>IH</sub> ,V <sub>IN</sub> =V <sub>IH</sub>	-	12	-	
Over current detection	loc	OUT	V <sub>STBY</sub> =V <sub>IH</sub> ,V <sub>IN</sub> =V <sub>IH</sub> , V <sub>DD</sub> =5V	6	13	-	Α
Over current protection off time	toff-duty	OUT	$V_{BAT}$ =12V, $R_L$ =0.1 $\Omega$ , $V_{DD}$ =5V, $V_{STBY}$ =V <sub>IH</sub> , $V_{IN}$ =V <sub>IH</sub>	3	7	12	ms
Load open detection	Rop	OUT	V <sub>STBY</sub> =V <sub>IH</sub> , V <sub>IN</sub> =V <sub>IL</sub> , V <sub>OUT</sub> =8 to 16V	10	300	1000	kΩ
resistance	$\Delta R_{op}$	OUT	V <sub>STBY</sub> =V <sub>IH</sub> , V <sub>IN</sub> =V <sub>IL</sub> , V <sub>OUT</sub> =8 to 16V	-	40	-	kΩ
Output datastics valtage	V <sub>OD</sub>	OUT	V <sub>STBY</sub> =V <sub>IH</sub> , V <sub>OUT</sub> =L→H	2	3	4	V
Output detection voltage	ΔV <sub>OD</sub>	OUT	V <sub>STBY</sub> =V <sub>IH</sub>	-	0.3	-	V
Output resistance	R <sub>OUT1</sub>	OUT	V <sub>STBY</sub> =V <sub>IH</sub> , V <sub>IN</sub> =V <sub>IL</sub> , V <sub>DD</sub> =4.5 to 5.5V T <sub>ch</sub> =25°C	75	100	125	kΩ
(output DMOS off)	R <sub>OUT2</sub>	OUT	V <sub>STBY</sub> =V <sub>IH</sub> , V <sub>IN</sub> =V <sub>IL</sub> , V <sub>DD</sub> =4.5 to 5.5V T <sub>ch</sub> =-40 to 125°C	60	100	140	kΩ
	Δt <sub>f</sub>	OUT		7.0	16.4	-	V/μs
0 '' 1 ' ''	ton	OUT	V <sub>STBY</sub> =V <sub>IH</sub> , V <sub>DD</sub> =5V,T <sub>ch</sub> =25°C,	-	0.8	5.0	μS
Switching time	Δt <sub>r</sub>	OUT	$V_{BAT}$ =12V, $R_L$ =5 $\Omega$ ,	7.0	15.5	-	V/μs
	t <sub>off</sub>	OUT	Slew rate : VOUT10% to 90%	-	2.1	5.0	μS

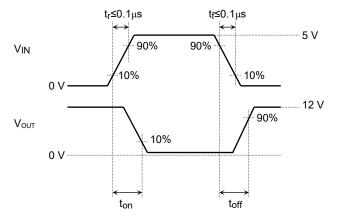
<sup>\*</sup>The condition of the typical value is T<sub>ch</sub>=25°C, V<sub>DD</sub>=5V.



## **Test Circuit**

Switching time ton, toff

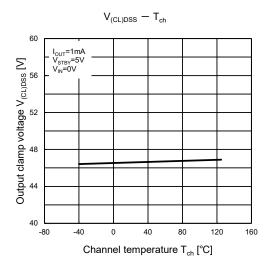


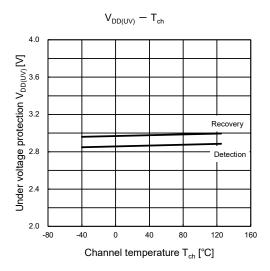


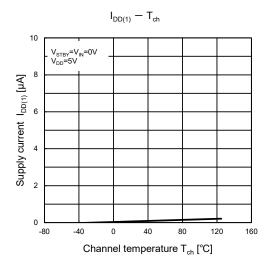


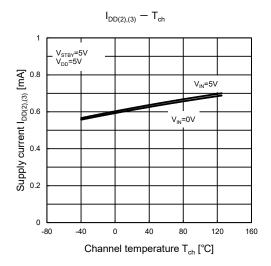
#### **Characteristic curves**

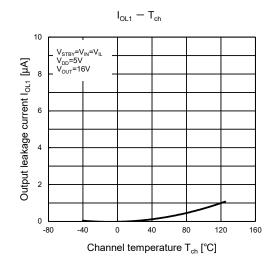
The below characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

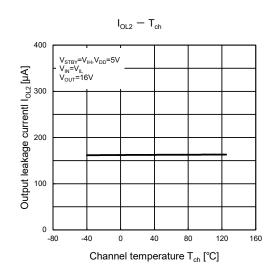




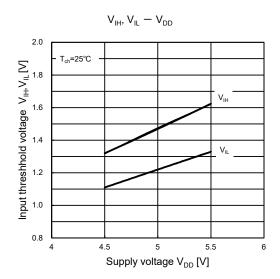


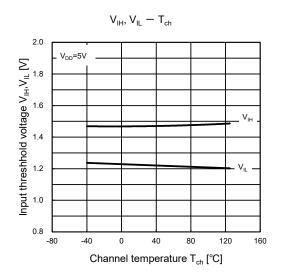


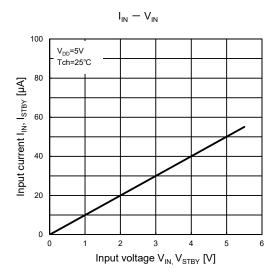


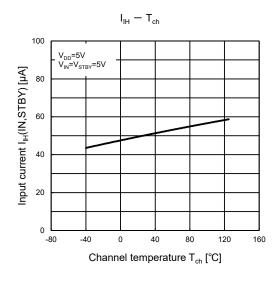


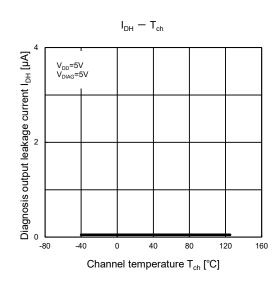


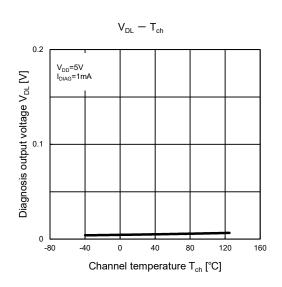




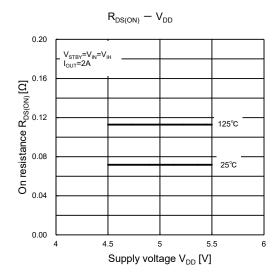


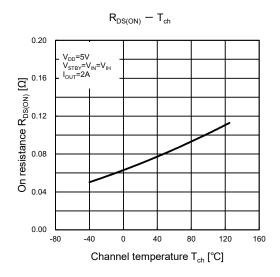


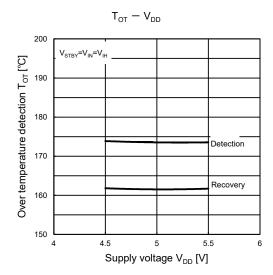


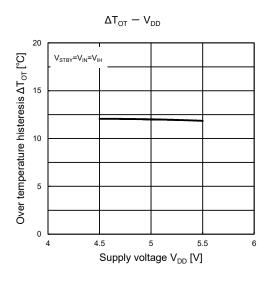


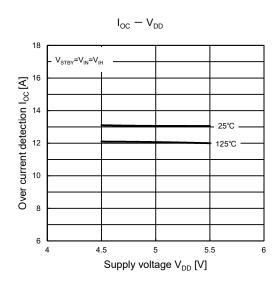


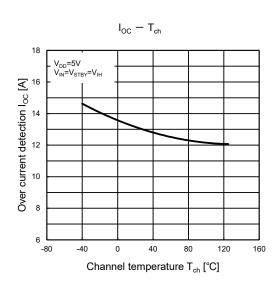




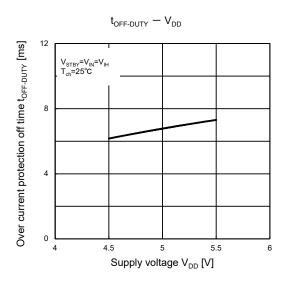


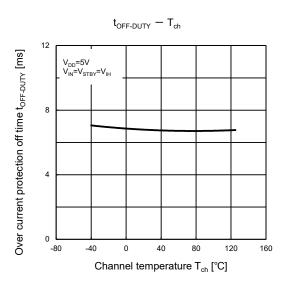


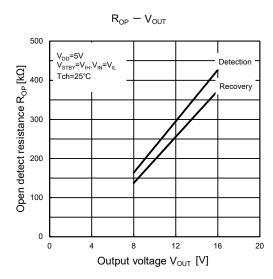


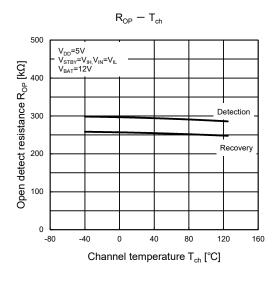


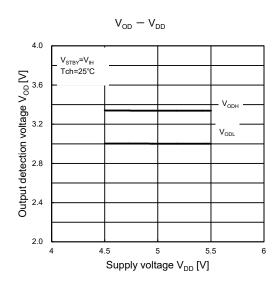


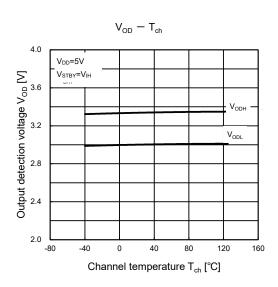




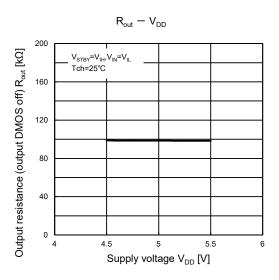


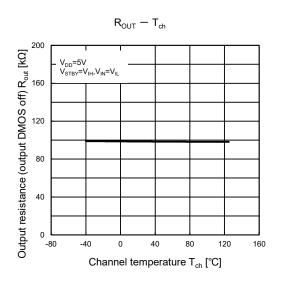


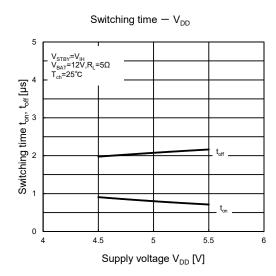


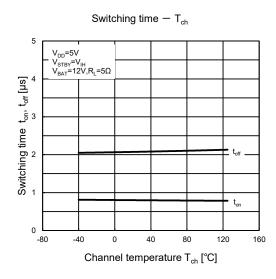


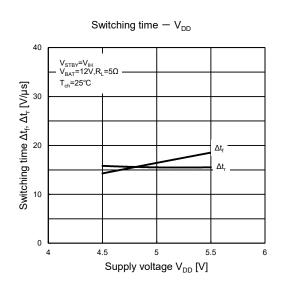


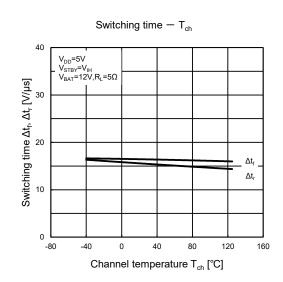




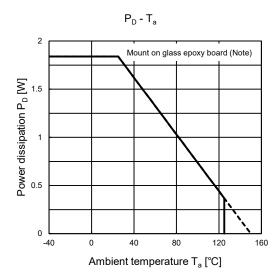


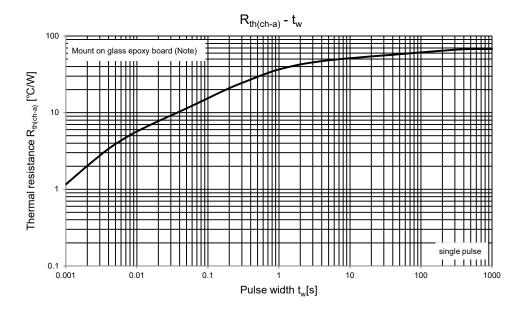












Note: Glass epoxy board

Material: FR-4 (4 layer)

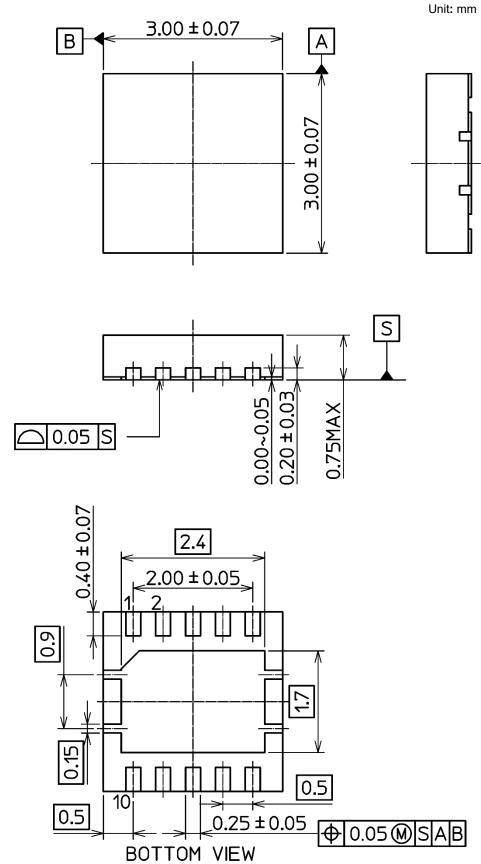
Board size: 76.2mm×114.3mm×1.6mm

Via: Ø0.3mm (2 point)



#### **Package Dimensions**

P-WSON10-0303-0.50-001



Weight: 0.02 g (Typ.)

Note: Please connect exposed pad to electrical open or GND.



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